

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2685240

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHING-FANG YU</td> <td>10/07/2013</td> </tr> <tr> <td>TING-HAO HSU</td> <td>10/08/2013</td> </tr> <tr> <td>CHIA-CHING HUANG</td> <td>10/08/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHING-FANG YU	10/07/2013	TING-HAO HSU	10/08/2013	CHIA-CHING HUANG	10/08/2013
Name	Execution Date								
CHING-FANG YU	10/07/2013								
TING-HAO HSU	10/08/2013								
CHIA-CHING HUANG	10/08/2013								
RECEIVING PARTY DATA									
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.								
Street Address:	NO. 8, LI-HSIN RD. 6								
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK								
City:	HSIN-CHU								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14045963</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14045963				
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Application Number:	14045963								
CORRESPONDENCE DATA									
Fax Number:									
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ATTORNEY DOCKET NUMBER:	2013-0777/24061.2607								
NAME OF SUBMITTER:	SCOTT MATTHEWS								
Signature:	/sm82918/								

Date:

01/16/2014

Total Attachments: 2

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Docket No.: 2013-0777/24061.2607
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- (1) Ching-Fang Yu of 5F., No. 80, Lane 200, Baoshan Road
East District, Hsin-Chu City 300
Taiwan, R.O.C.
- (2) Ting-Hao Hsu of 8F.-2, No. 25, Jianjhong 1st Road
East District, Hsin-Chu City 300
Taiwan, R.O.C.
- (3) Chia-Ching Huang of No. 13, Pinglin Road, Su-ao Township
Yilan County, 270, Taiwan R.O.C.

have invented certain improvements in

METHOD FOR INTEGRATED CIRCUIT FABRICATION

for which we have filed an application for Letters Patent of the United States of America on October 4, 2013, as U.S. Serial No. 14/045,963; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ching-Fang Yu

Residence Address: 5F., No. 80, Lane 200, Baoshan Road
East District, Hsin-Chu City 300, Taiwan, R.O.C.

Dated: 2013. 10/7

Ching-Fang Yu
Inventor Signature

Inventor Name: Ting-Hao Hsu

Residence Address: 8F.-2, No. 25, Jianjhong 1st Road
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Dated: 2013. 10/8

Ting-Hao Hsu
Inventor Signature

Inventor Name: Chia-Ching Huang

Residence Address: No. 13, Pinglin Road, Su-ao Township
Yilan County, 270, Taiwan R.O.C.

Dated: 2013. 10. 8

Chia-Ching Huang
Inventor Signature